

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

- 1-9. (Canceled)
10. (Previously Presented) An abrasive for polishing a substrate comprising silica in an amount of 50 wt% or more, the abrasive comprising a sol, which includes particles dispersed in an aqueous medium, wherein:
  - the particles comprise as a main component crystalline cerium oxide of cubic system and as an additional component a lanthanum compound, neodymium compound or a combination thereof;
  - the additional component is contained in an  $X/(Ce + X)$  molar ratio of 0.005 to 0.15 in which X is lanthanum atoms, neodymium atoms or a combination thereof;
  - the particles are present in the abrasive in an amount of 0.1 to 50 wt%;
  - the particles have a particle size of 50 to 150 nm;
  - the particles have a specific surface area of 2 to 200 m<sup>2</sup>/g; and
  - the abrasive has a pH of 3 to 6 or 8 to 10.
11. (Canceled)
12. (Previously Presented) An abrasive according to claim 10, wherein the additional component is a lanthanum compound.
13. (Previously Presented) An abrasive according to claim 10, wherein the additional component is a neodymium compound.
- 14-18. (Canceled)
19. (Previously Presented) An abrasive for polishing a rock crystal, a quartz glass for a photomask, a semiconductor device or a hard disk made of glass, the abrasive comprising a sol, which includes particles dispersed in an aqueous medium, wherein:

the particles comprise as a main component crystalline cerium oxide of cubic system and as an additional component a lanthanum compound, neodymium compound or a combination thereof;

the additional component is contained in an  $X/(Ce + X)$  molar ratio of 0.005 to 0.15 in which X is lanthanum atoms, neodymium atoms or a combination thereof;

the particles are present in the abrasive in an amount of 0.1 to 50 wt%;

the particles have a particle size of 50 to 150 nm;

the particles have a specific surface area of 2 to 200 m<sup>2</sup>/g; and

the abrasive has a pH of 3 to 6 or 8 to 10.

20. (Previously Presented) An abrasive according to claim 19, wherein the additional component is a lanthanum compound.

21. (Previously Presented) An abrasive according to claim 19, wherein the additional component is a neodymium compound.

22. (Previously Presented) An abrasive for polishing an organic film with the Chemical Mechanical Polishing method, an Inter Layer Dielectric (ILD), or a shallow trench isolation of a semiconductor device, the abrasive comprising a sol, which includes particles dispersed in an aqueous medium, wherein:

the particles comprise as a main component crystalline cerium oxide of cubic system and as an additional component a lanthanum compound, neodymium compound or a combination thereof;

the additional component is contained in an  $X/(Ce + X)$  molar ratio of 0.005 to 0.15 in which X is lanthanum atoms, neodymium atoms or a combination thereof;

the particles are present in the abrasive in an amount of 0.1 to 50 wt%;

the particles have a particle size of 50 to 150 nm;

the particles have a specific surface area of 2 to 200 m<sup>2</sup>/g; and

the abrasive has a pH of 3 to 6 or 8 to 10.

23. (Previously Presented) An abrasive according to claim 19, wherein the additional component is a lanthanum compound.

24. (Previously Presented) An abrasive according to claim 19, wherein the additional component is a neodymium compound.

25. (New) An abrasive according to claim 19, wherein the sol further comprises at least one selected from the group consisting of a water soluble polymer, an anionic surfactant, a nonionic surfactant and a cationic surfactant.